

FIG. 1A

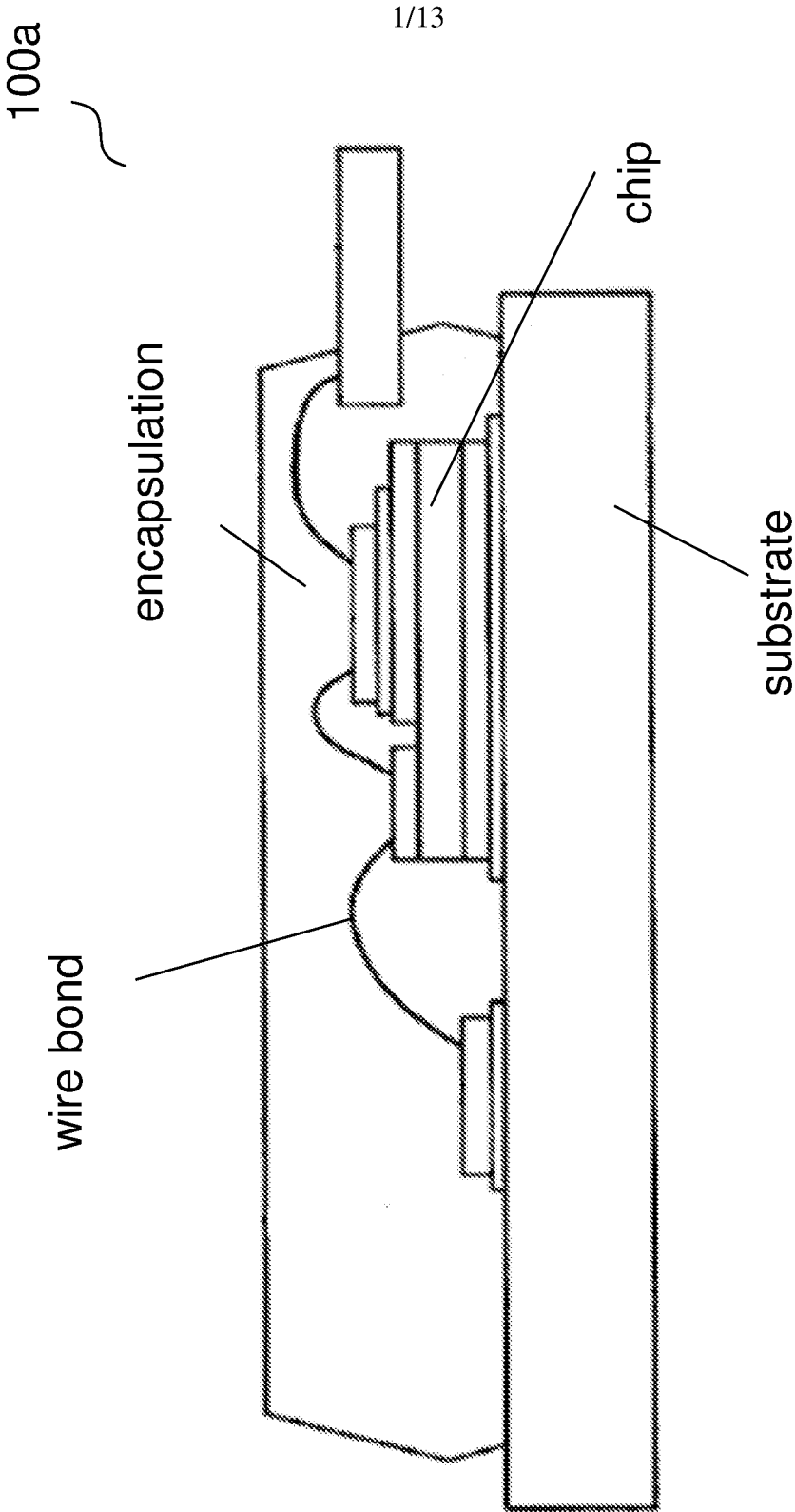
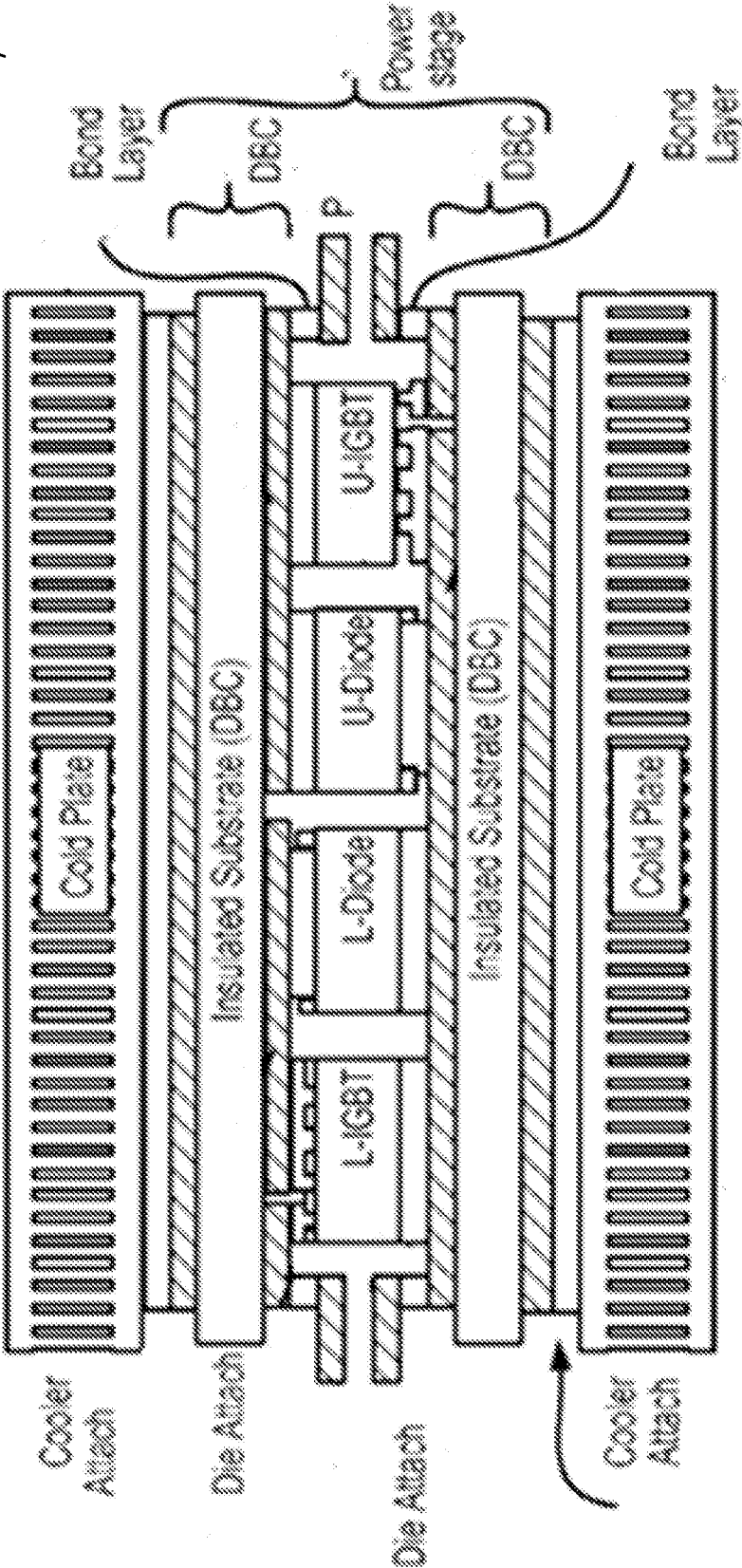
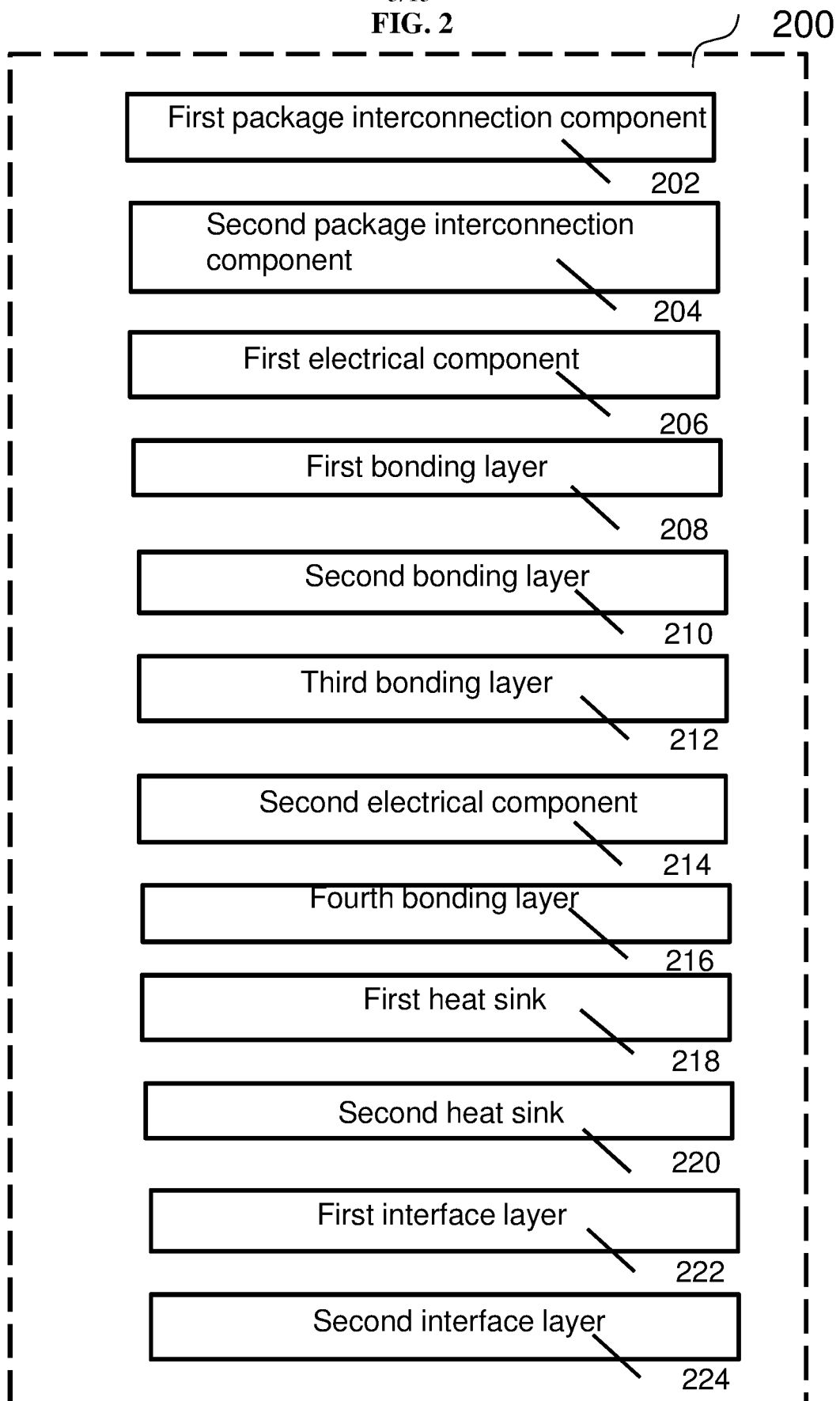


FIG. 1B

100b



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FIG. 2

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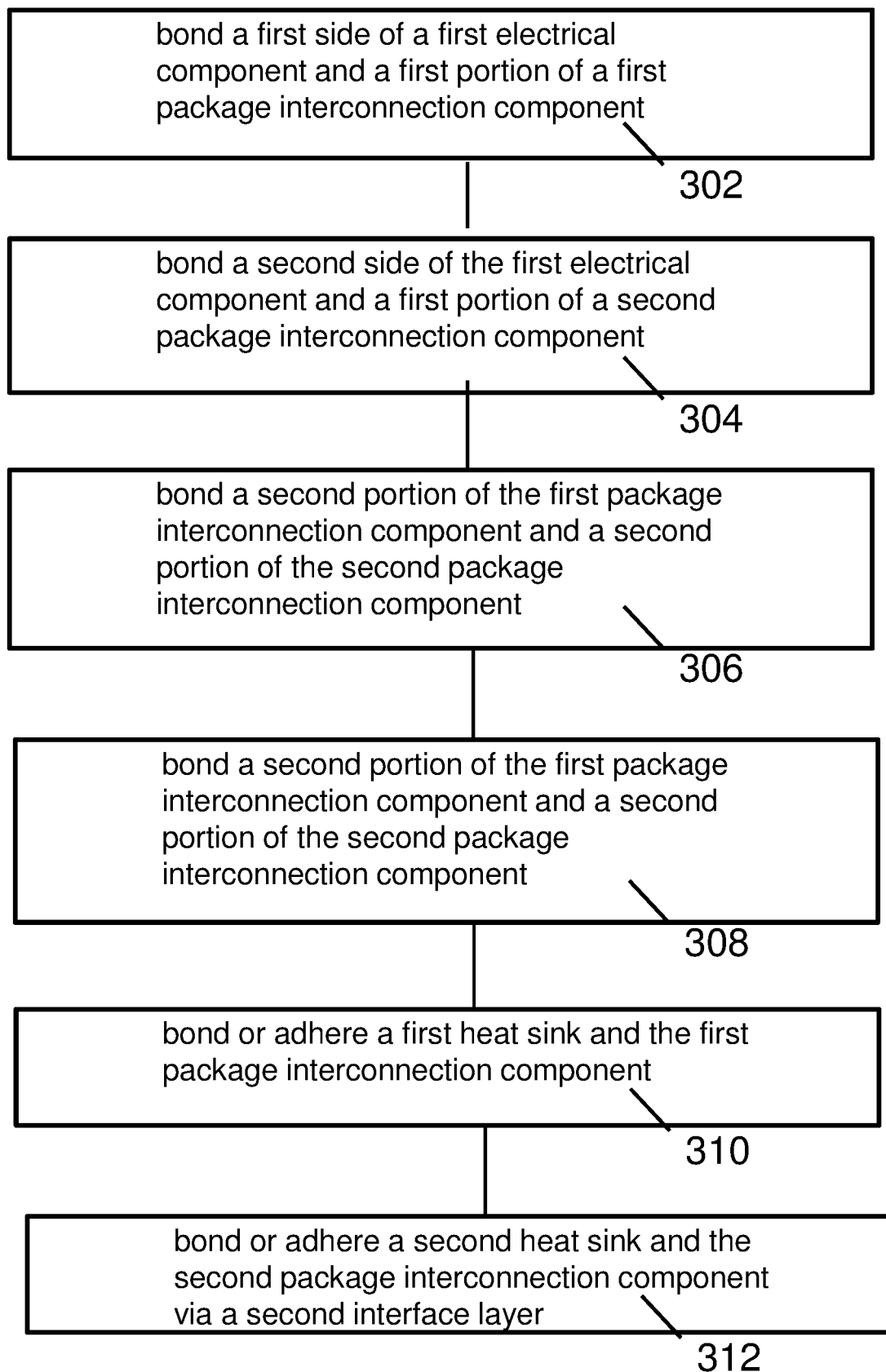
FIG. 3

FIG. 4A

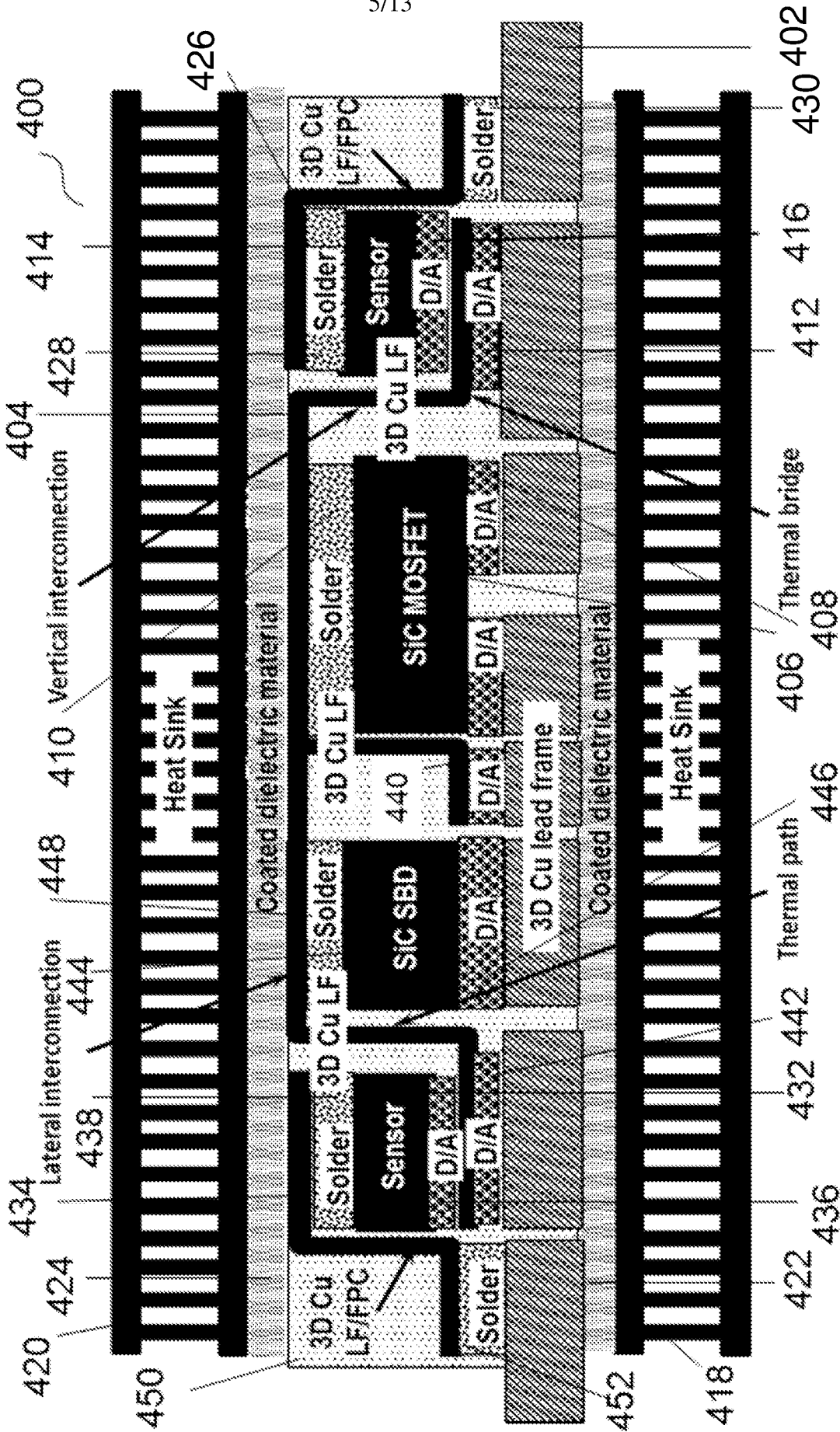


FIG. 4B

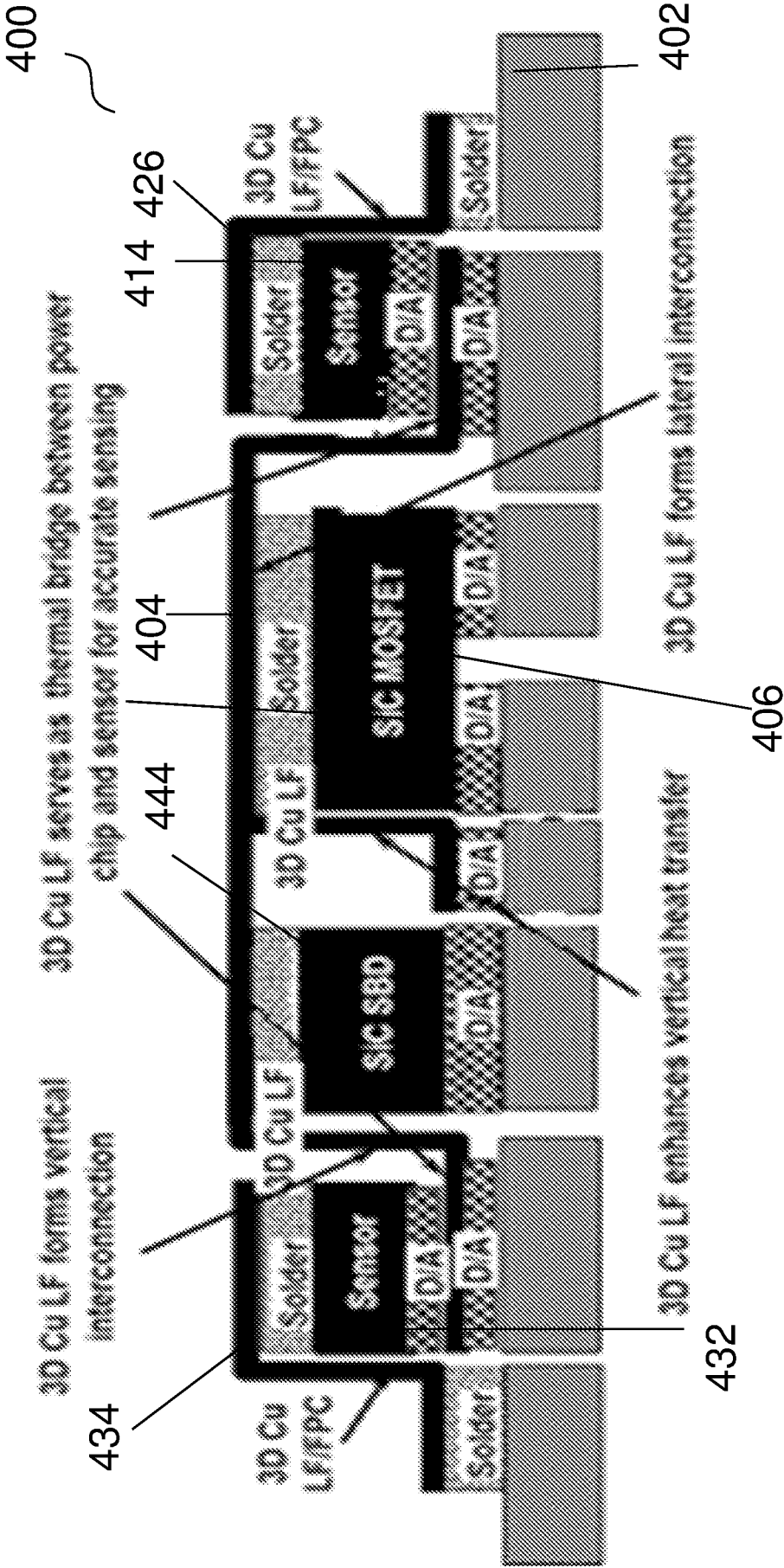
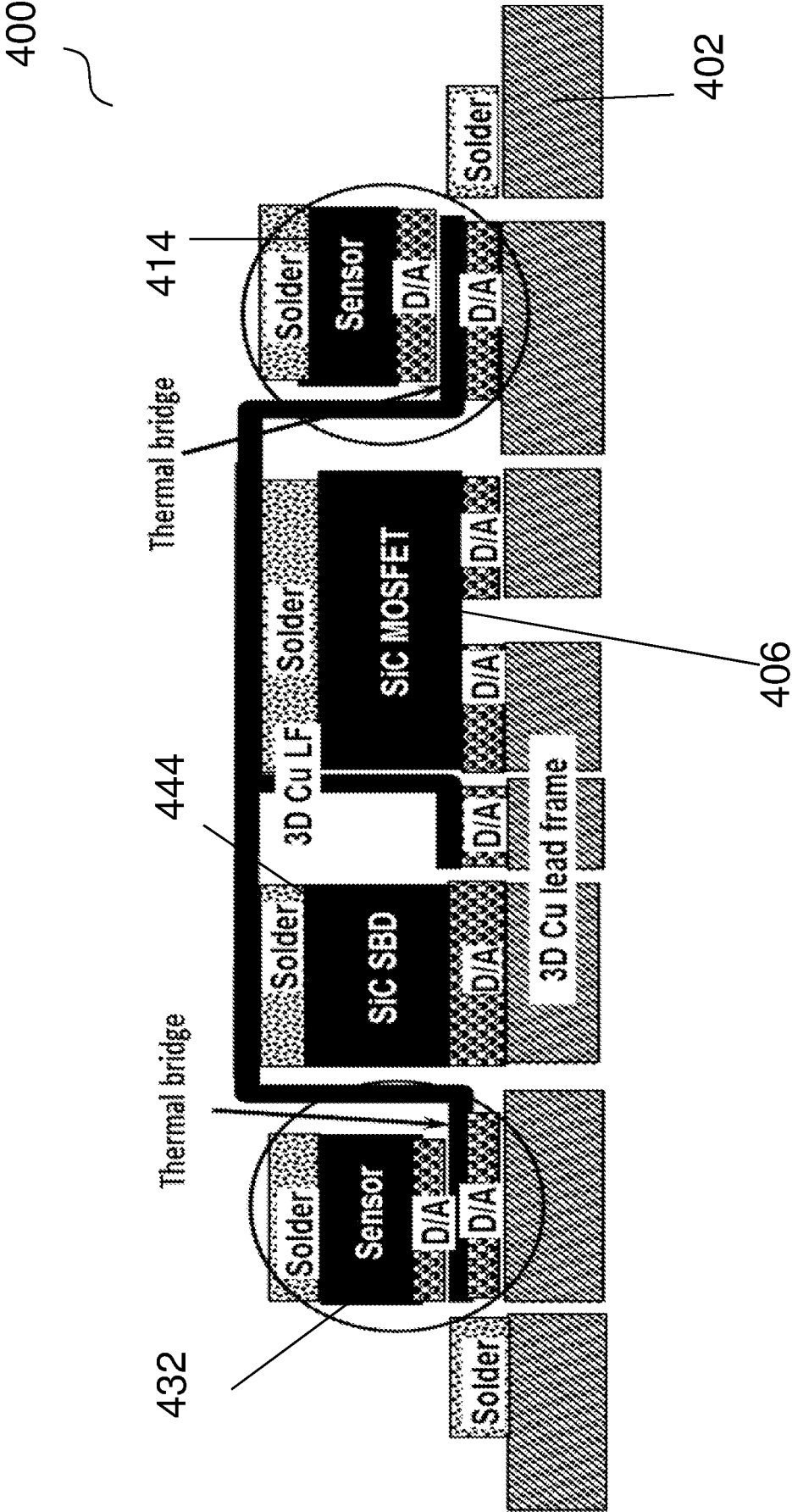
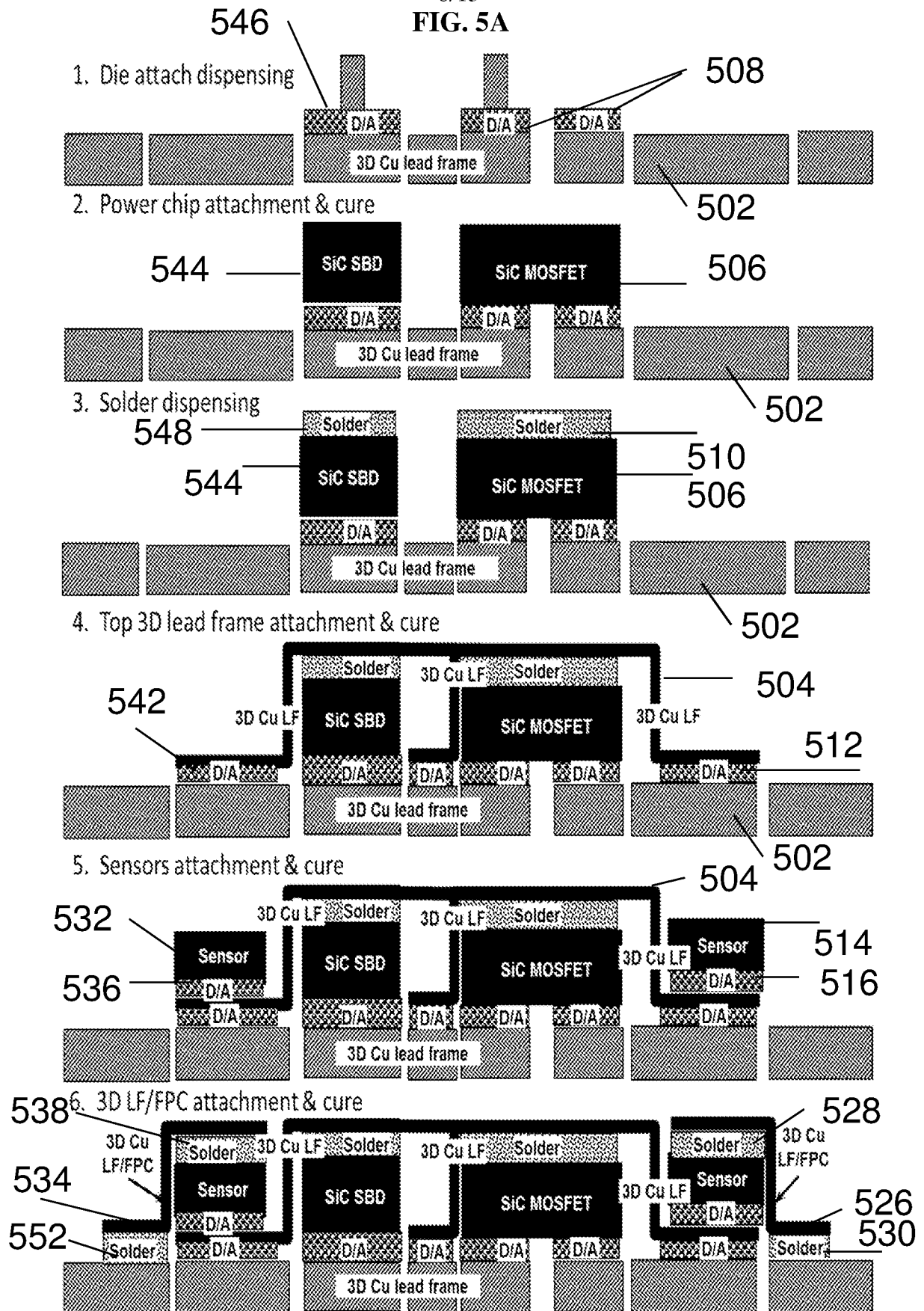


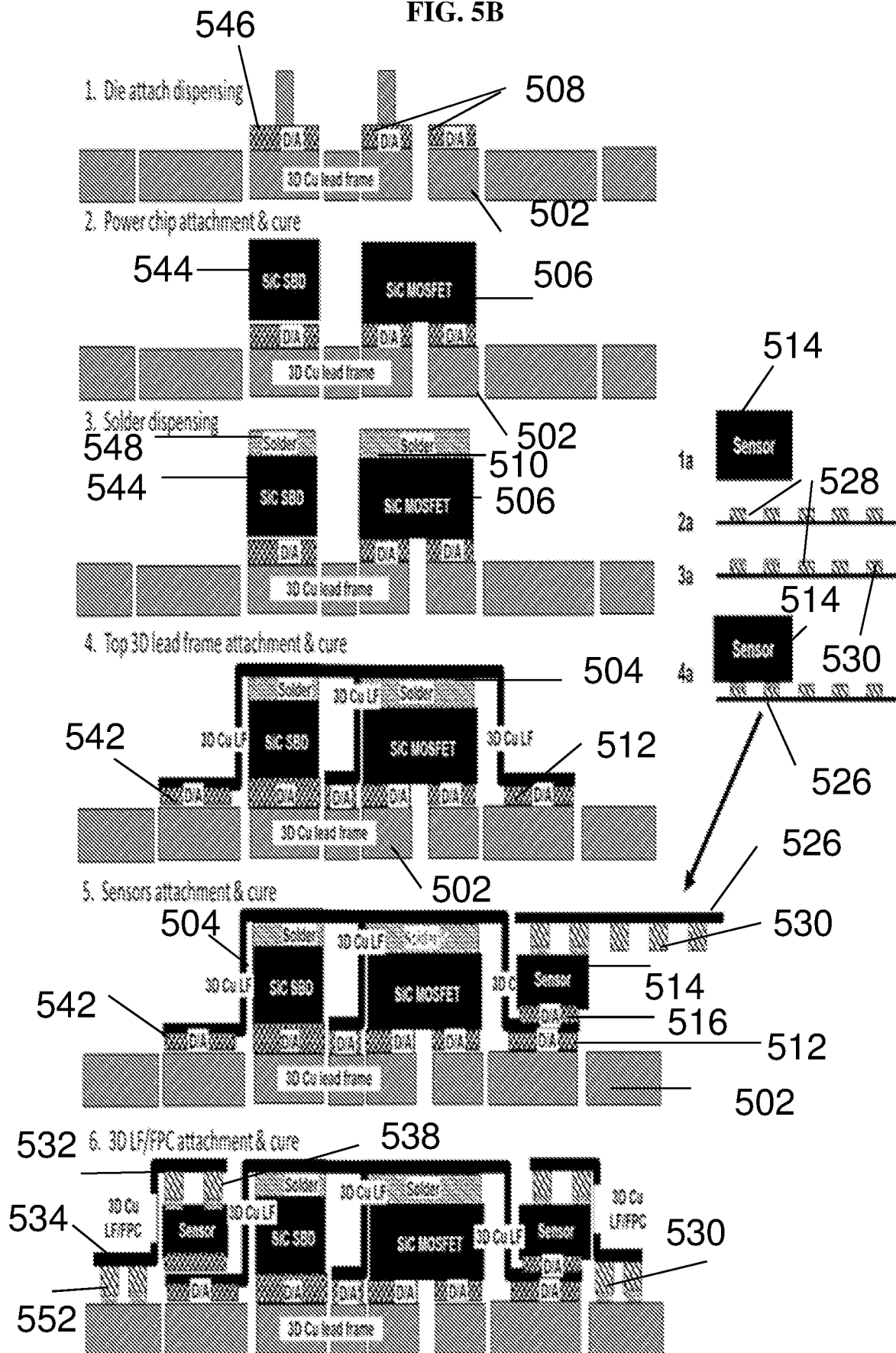
FIG. 4C



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FIG. 5A

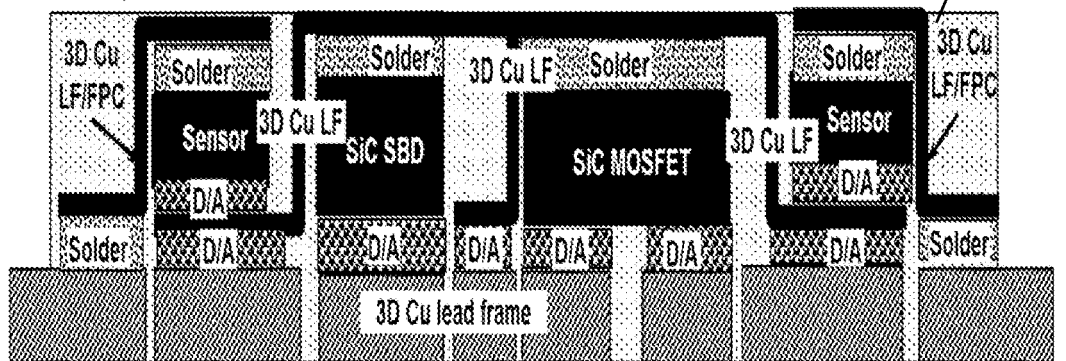
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FIG. 5B

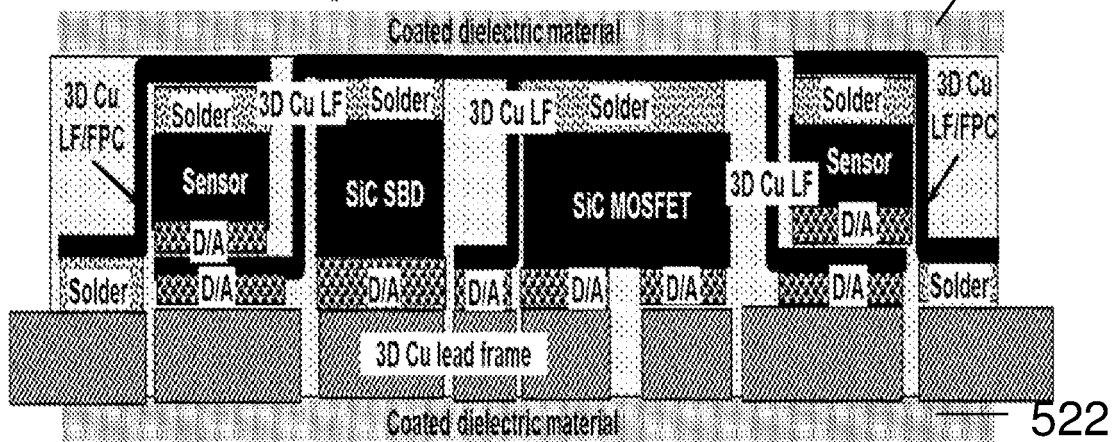


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FIG. 5C

7. Molding



8. Dielectric material coating



9. Heat sink attachment

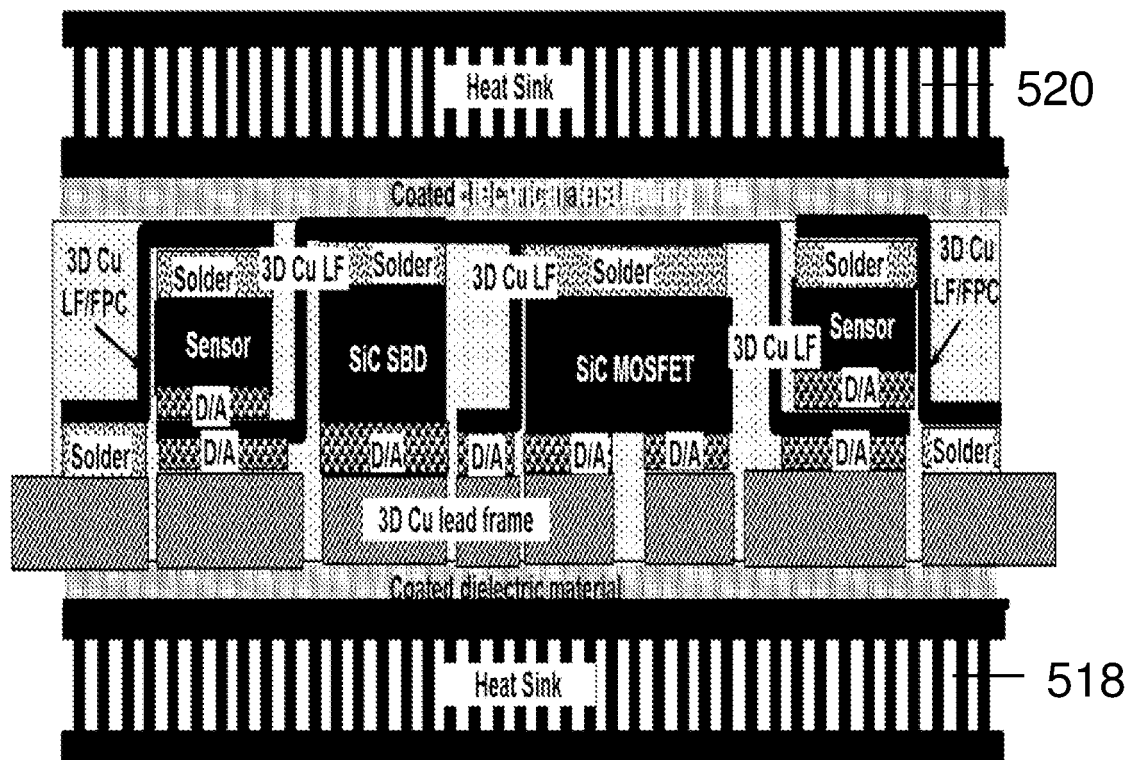


FIG. 6A

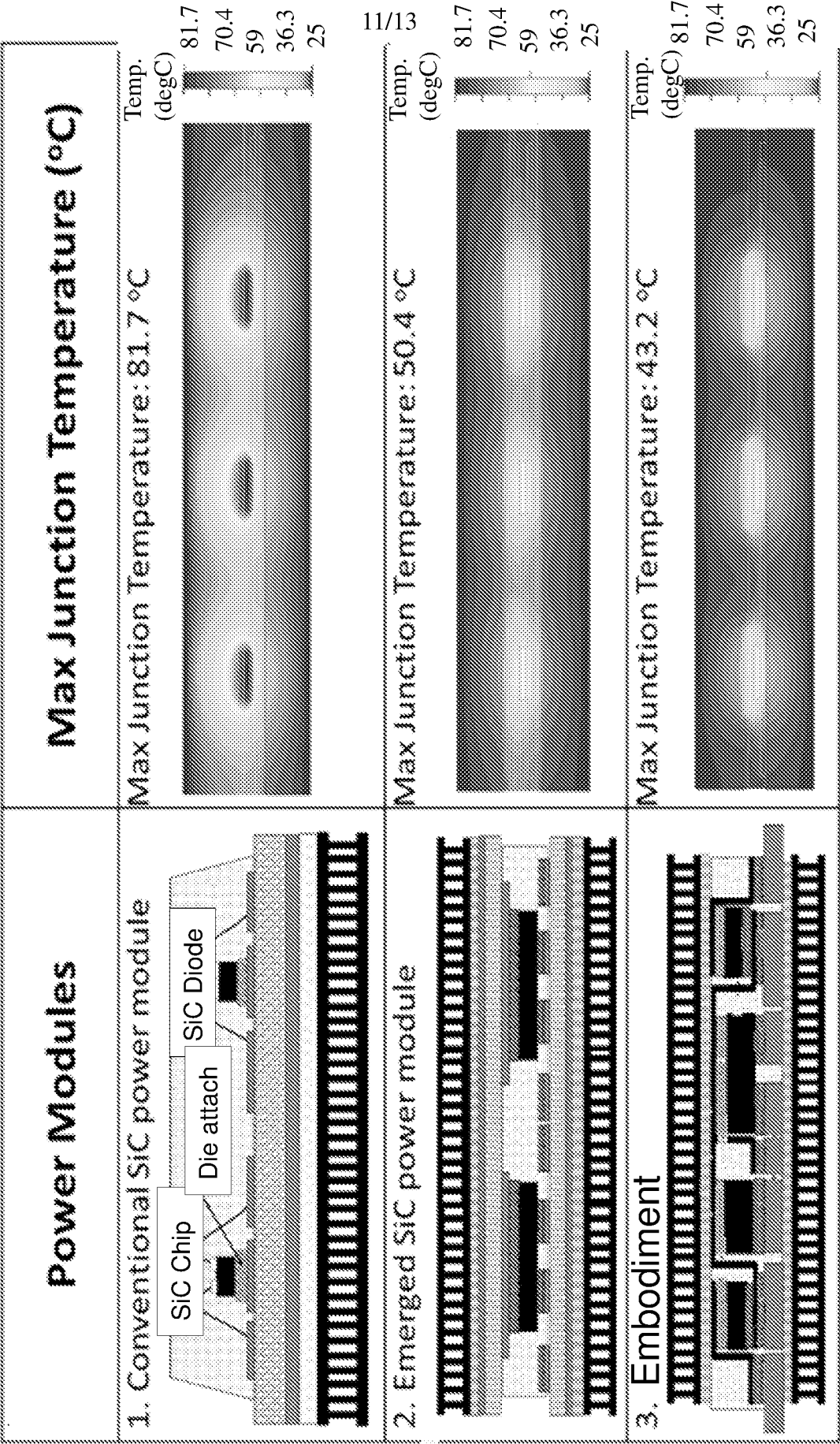


FIG. 6B

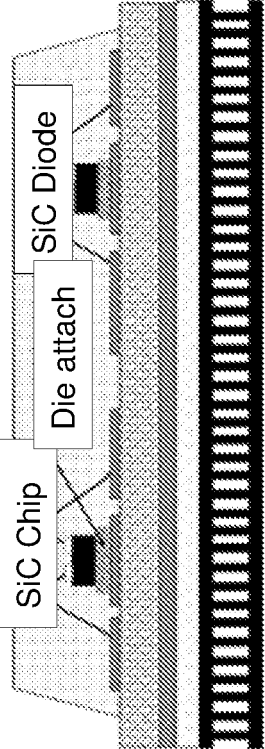
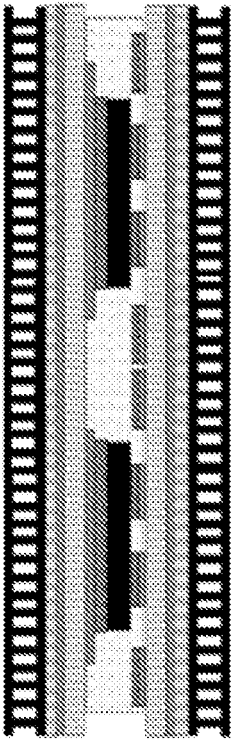
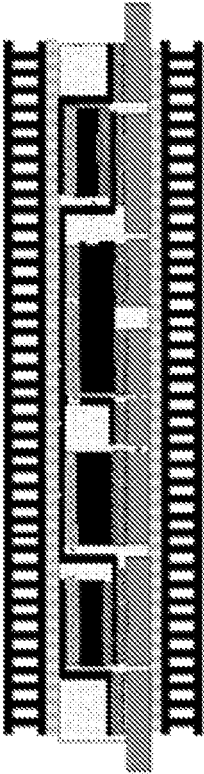
Power Modules	Junction to Case Thermal Resistance (°C/W)
1. Conventional SiC power module 	0.315
2. Emerged SiC power module 	0.141
3. Embodiment 	0.101

FIG. 6C

